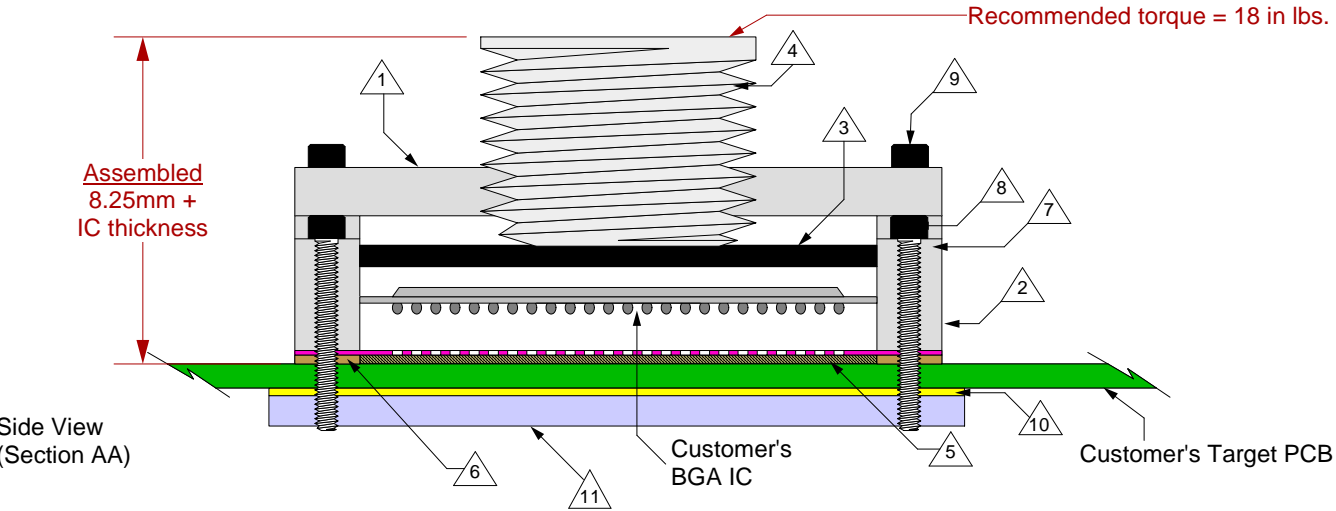
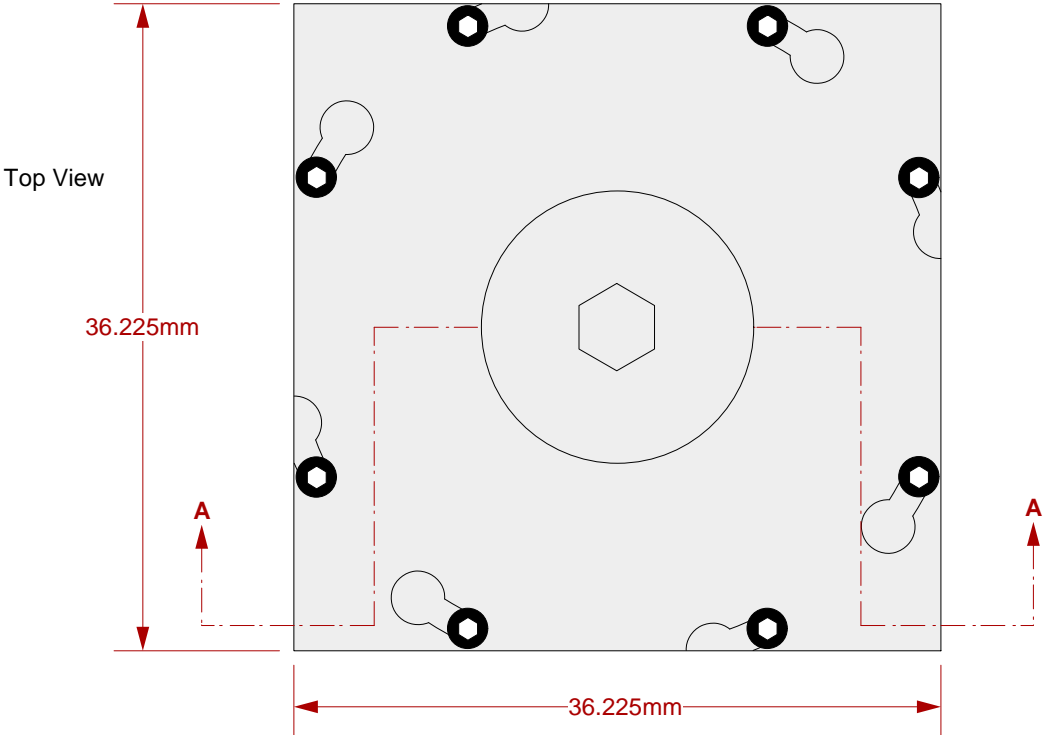



# GHz BGA Socket - Direct mount, solderless

## Features

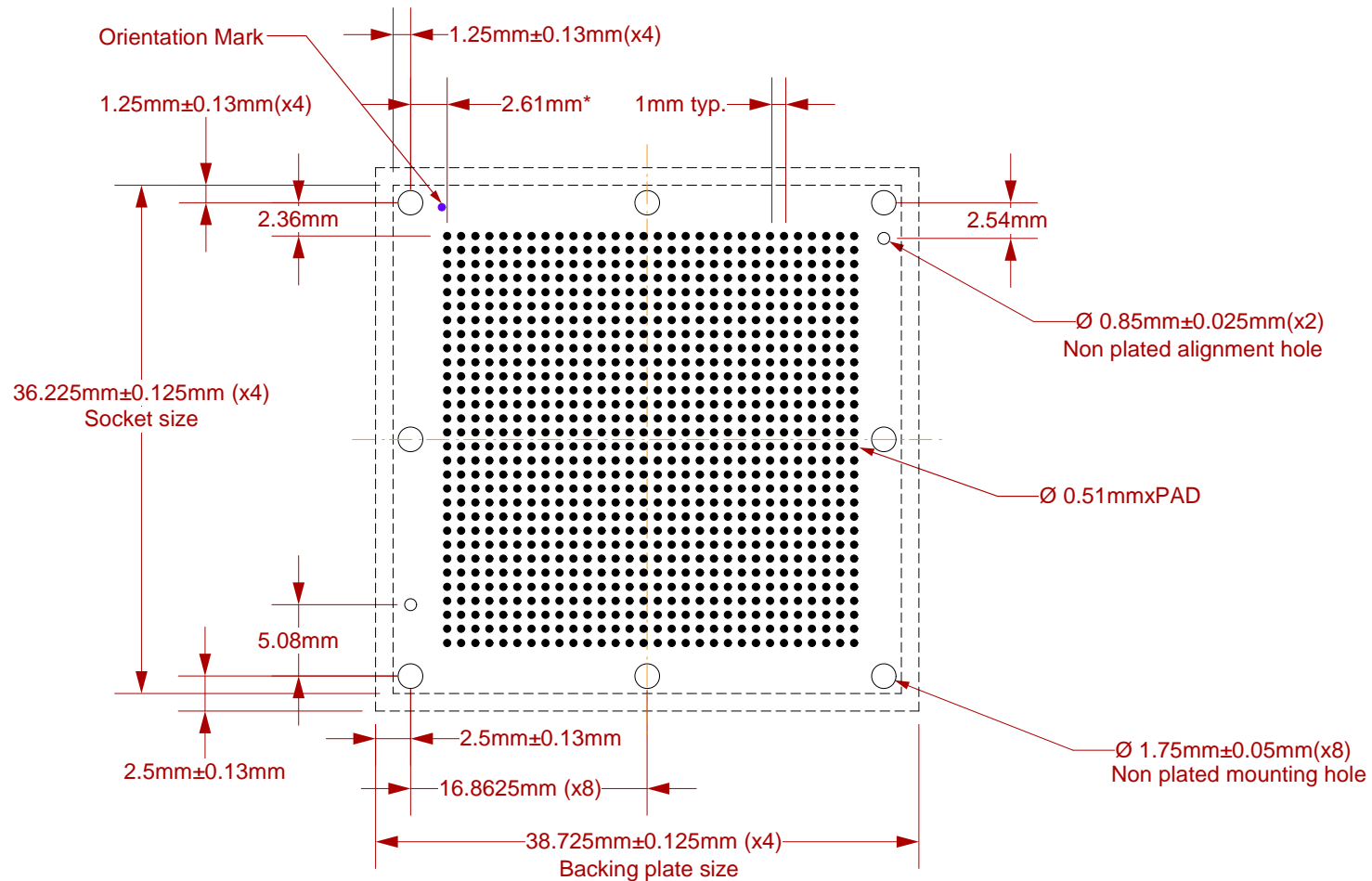
- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid



- △ 1 Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- △ 2 Socket base: Black anodized Aluminum. Thickness = 6.5mm.
- △ 3 Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- △ 4 Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- △ 5 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- △ 6 Elastomer Guide: Cirlex or equivalent. Thickness = 0.475mm.
- △ 7 Ball Guide: Kapton polyimide.
- △ 8 Socket base screw: Socket head cap, alloy steel with black oxide finish, 0-80 fine thread, 15.875mm long.
- △ 9 Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- △ 10 Insulation Plate: FR4/G10, Thickness = 1.59mm.
- △ 11 Backing Plate: Black anodized Aluminum. Thickness = 6.35mm.

<b>SG-BGA-8000 Drawing</b>		Status: Released	Scale: -	Rev: C
 <p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: J. Glab		Date: 3/16/07	
	File: SG-BGA-8000 Dwg		Modified: 7/22/09, AE	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.




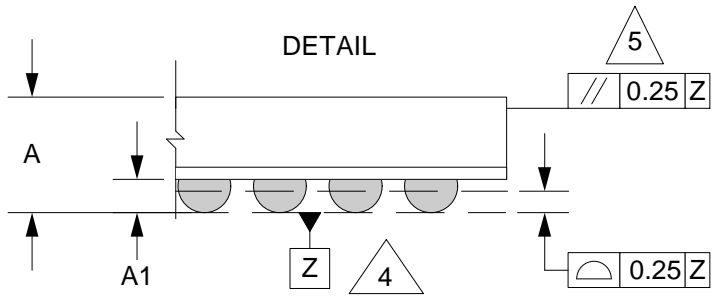
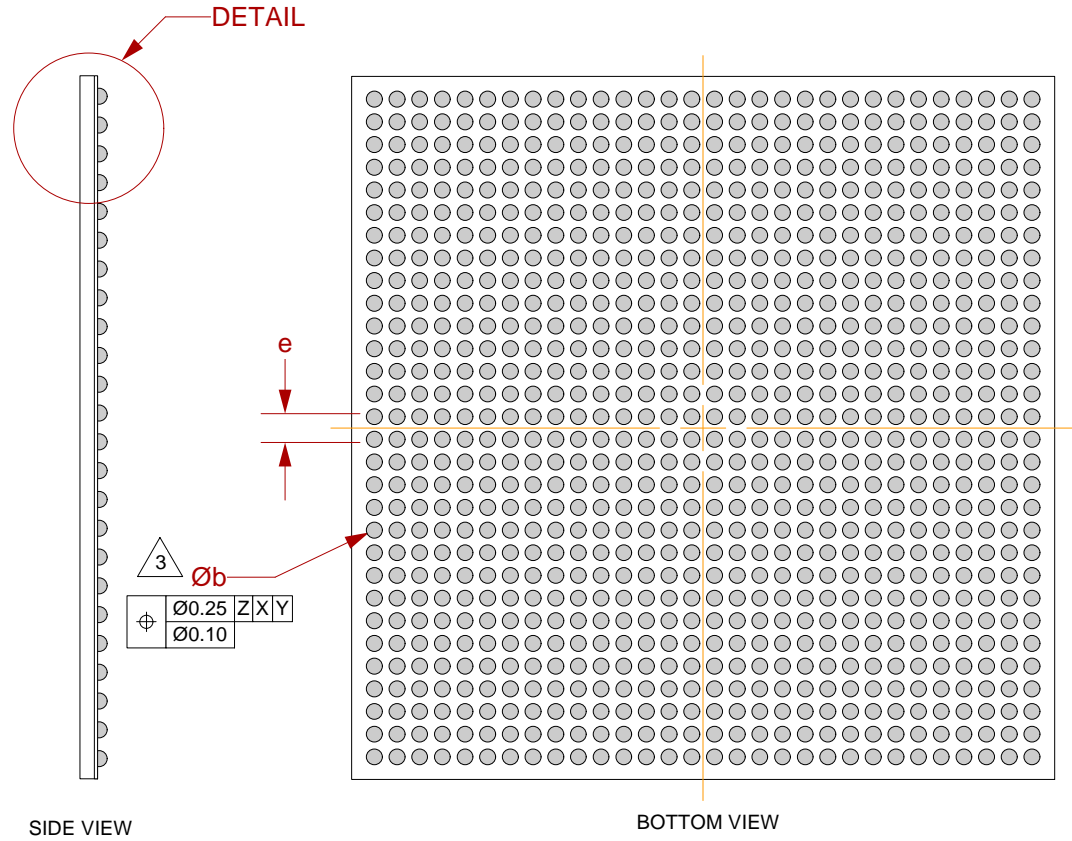
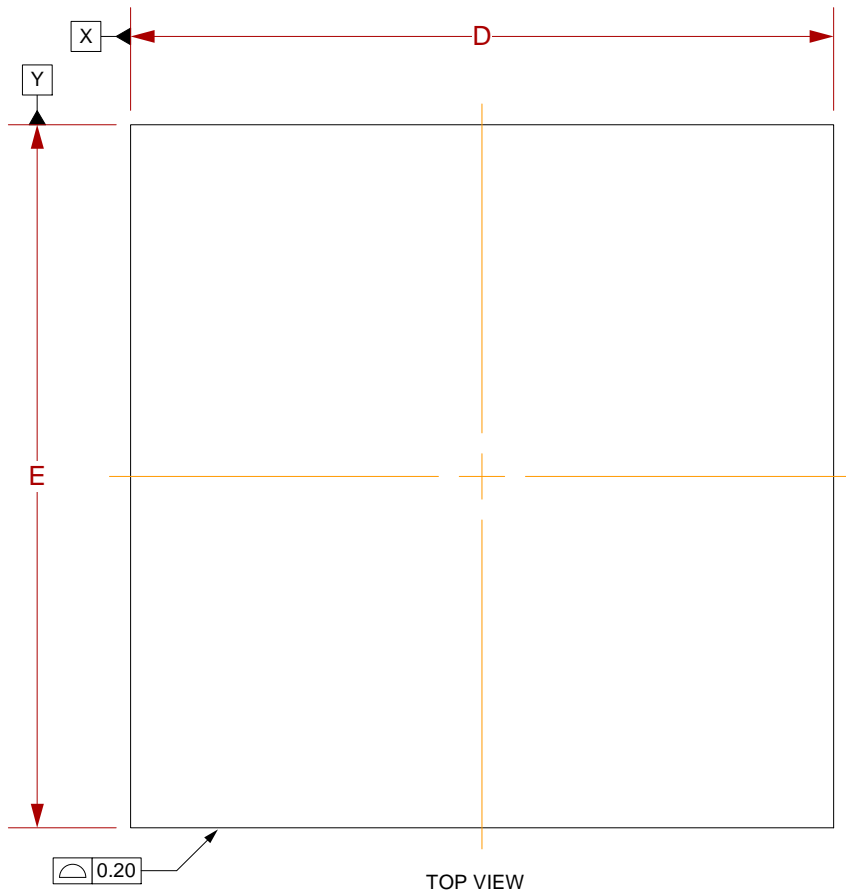
Target PCB Recommendations

Total thickness: 2.4mm min.  
Plating: Gold or Solder finish  
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances:  $\pm 0.025\text{mm}$  [ $\pm 0.001''$ ] unless stated otherwise.


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	<p>Drawing: J. Glab</p>	<p>Date: 3/16/07</p>		
	<p>File: SG-BGA-8000 Dwg</p>	<p>Modified: 7/22/09, AE</p>		



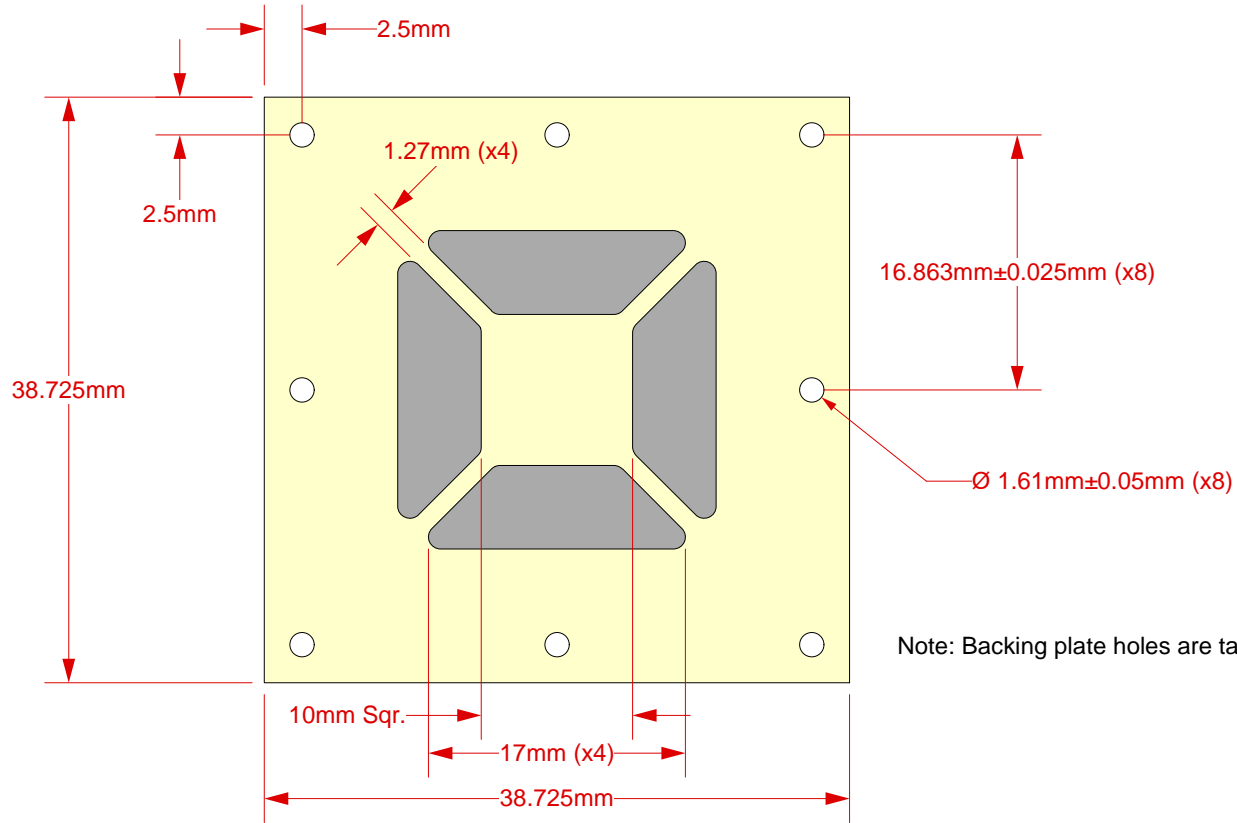
1. Dimensions are in millimeters.
  2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- △3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
  - △4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
  - △5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		3.42
A1	0.3	
b		0.7
D	31.00 BSC	
E	31.00 BSC	
e	1.0 BSC	

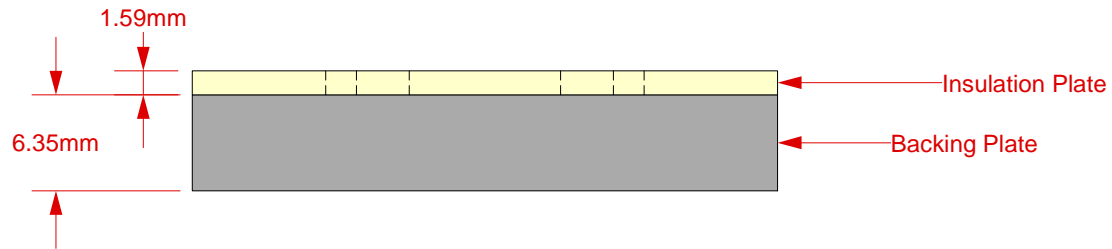
Array 30x30

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	<p>Drawing: J. Glab</p>			<p>Date: 3/16/07</p>		
	<p>File: SG-BGA-8000 Dwg</p>			<p>Modified: 7/22/09, AE</p>		


**Top View**



**Side View**



Description: Insulation Plate and Backing Plate

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	<p>Drawing: J. Glab</p>			<p>Date: 3/16/07</p>	
	<p>File: SG-BGA-8000 Dwg</p>			<p>Modified: 7/22/09, AE</p>	